


ELECTRONIC INFORMATION DISCLOSURE STATEMENT

Electronic Version v18

Stylesheet Version v18.0

Title of Invention	HIGH-SPEED DIAPHRAGM VALVE FOR ATOMIC LAYER DEPOSITION						
<p>Application Number : 10/609134 </p> <p>Confirmation Number: 6738</p> <p>First Named Applicant: Jarmo Maula</p> <p>Attorney Docket Number: 11429/13:1</p> <p>Art Unit:</p> <p>Examiner:</p> <p>Search string: (5520001 or 6752387 or 20030121608).pn</p>							
US Patent Documents							
Note: Applicant is not required to submit a paper copy of cited US Patent Documents							
init	Cite.No.	Patent No.	Date	Patentee	Kind	Class	Subclass
KL	1	5520001	1996-05-28	Miyamoto et al.		62	50.2
KL	2	6752387	2004-06-22	Nishizato et al.	B1	261	62
US Published Applications							
Note: Applicant is not required to submit a paper copy of cited US Published Applications							
init	Cite.No.	Pub. No.	Date	Applicant	Kind	Class	Subclass
KL	1	20030121608	2003-07-03	Chen et al.	A1	156	345.33
Signature							
Examiner Name				Date			
Kevin Lee				5/7/05			